



Chipsmall Limited consists of a professional team with an average of over 10 year of expertise in the distribution of electronic components. Based in Hongkong, we have already established firm and mutual-benefit business relationships with customers from,Europe,America and south Asia,supplying obsolete and hard-to-find components to meet their specific needs.

With the principle of "Quality Parts,Customers Priority,Honest Operation,and Considerate Service",our business mainly focus on the distribution of electronic components. Line cards we deal with include Microchip,ALPS,ROHM,Xilinx,Pulse,ON,Everlight and Freescale. Main products comprise IC,Modules,Potentiometer,IC Socket,Relay,Connector.Our parts cover such applications as commercial,industrial, and automotives areas.

We are looking forward to setting up business relationship with you and hope to provide you with the best service and solution. Let us make a better world for our industry!



## Contact us

Tel: +86-755-8981 8866 Fax: +86-755-8427 6832

Email & Skype: info@chipsmall.com Web: www.chipsmall.com

Address: A1208, Overseas Decoration Building, #122 Zhenhua RD., Futian, Shenzhen, China





Is Now Part of



**ON Semiconductor®**

To learn more about ON Semiconductor, please visit our website at  
[www.onsemi.com](http://www.onsemi.com)

Please note: As part of the Fairchild Semiconductor integration, some of the Fairchild orderable part numbers will need to change in order to meet ON Semiconductor's system requirements. Since the ON Semiconductor product management systems do not have the ability to manage part nomenclature that utilizes an underscore (\_), the underscore (\_) in the Fairchild part numbers will be changed to a dash (-). This document may contain device numbers with an underscore (\_). Please check the ON Semiconductor website to verify the updated device numbers. The most current and up-to-date ordering information can be found at [www.onsemi.com](http://www.onsemi.com). Please email any questions regarding the system integration to [Fairchild\\_questions@onsemi.com](mailto:Fairchild_questions@onsemi.com).

ON Semiconductor and the ON Semiconductor logo are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.



# FAN3850A

## Microphone Pre-Amplifier with Digital Output

### Features

- Optimized for Mobile Handset and Notebook PC Microphone Applications
- Accepts Input from Electret Condenser Microphones (ECM)
- Pulse Density Modulation (PDM) Output
- Standard 5-Wire Digital Interface
- 16dB Gain
- Low Input Capacitance, High PSR, 20 kHz Pre-Amplifier
- Low-Power 1.5  $\mu$ A Sleep Mode
- Typical 470  $\mu$ A Supply Current
- SNR of 62 dB(A) for 16 dB Gain Respectively
- Total Harmonic Distortion 0.02%
- Input Clock Frequency Range of 1-4 MHz
- Integrated Low Drop-Out Regulator (LDO)
- Small 1.26 mm x 0.86 mm 6-Ball WLCSP Package

### Description

The FAN3850A integrates a pre-amplifier, LDO, and ADC that converts Electret Condenser Microphone (ECM) outputs to digital Pulse Density Modulation (PDM) data streams. The pre-amplifier accepts analog signals from the ECM and drives an over-sampled sigma delta Analog-to-Digital Converter (ADC) and outputs PDM data. The PDM digital audio has the advantage of noise rejection and easy interface to mobile handset processors.

The FAN3850A features an integrated LDO and is powered from the system supply rails up to 3.63 V, with low power consumption of only 0.85 mW and less than 20  $\mu$ W in Power-Down Mode.

### Applications

- Electret Condenser Microphones with Digital Output
- Mobile Handset
- Headset Accessories
- Personal Computer (PC)

### Ordering Information

Part Number	Operating Temperature Range	Package	Packing Method
FAN3850AUC16X	-30°C to +85°C	6 Ball, Wafer-Level Chip-Scale Package (WLCSP)	3000 Units on Tape & Reel

## Block Diagram

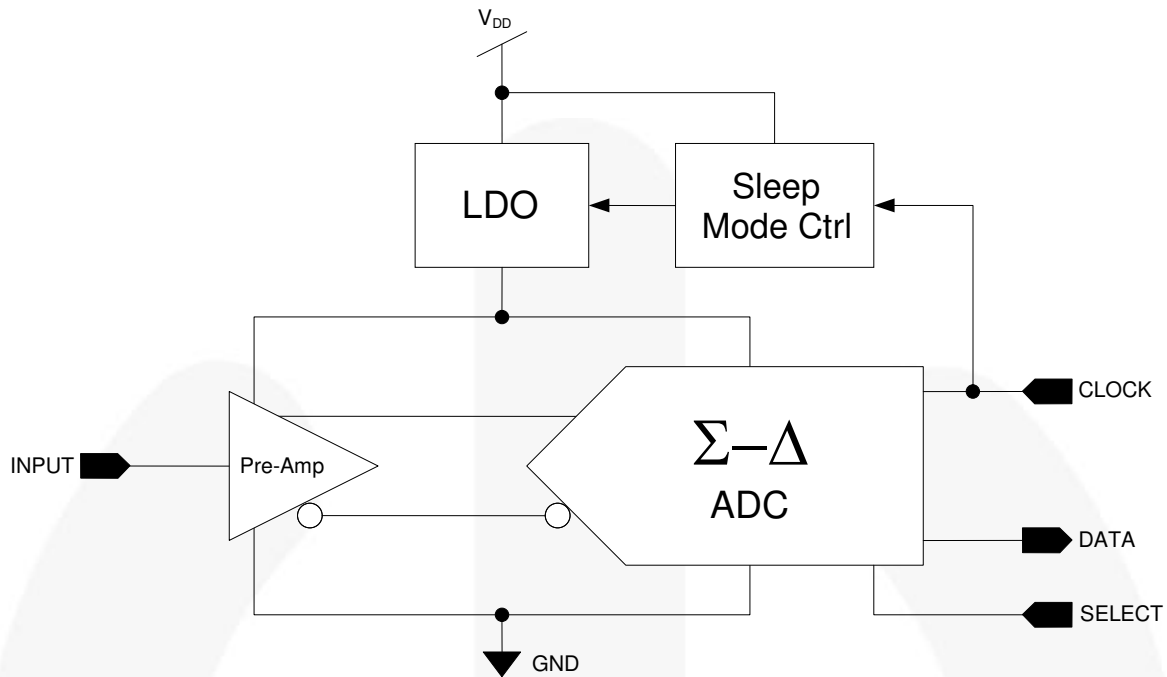


Figure 1. Block Diagram

## Pin Configuration

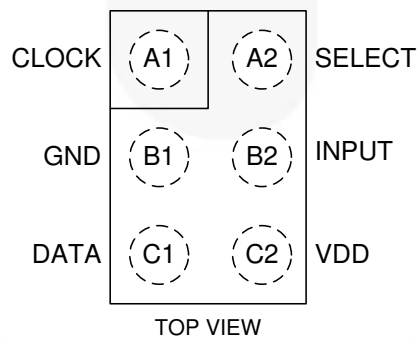


Figure 2. Pin Assignments

## Pin Definitions

Pin#	Name	Type	Description
A1	CLOCK	Input	Clock Input
B1	GND	Input	Ground Pin
C1	DATA	Output	PDM Output – 1 Bit ADC
A2	SELECT	Input	Rising or Falling Clock Edge Select
B2	INPUT	Input	Microphone Input
C2	VDD	Input	Device Power Pin

## Absolute Maximum Ratings

Stresses exceeding the absolute maximum ratings may damage the device. The device may not function or be operable above the recommended operating conditions and stressing the parts to these levels is not recommended. In addition, extended exposure to stresses above the recommended operating conditions may affect device reliability. The absolute maximum ratings are stress ratings only.

Symbol	Parameter	Min.	Max.	Unit
V <sub>DD</sub>	DC Supply Voltage	-0.3	4.0	V
V <sub>IO</sub>	Digital I/O	-0.3	V <sub>DD</sub> +0.3	V
	Microphone Input	-0.3	2.2	
ESD	Human Body Model, JESD22-A114, All Pins Except Microphone Input	±7		kV
	Human Body Model, JESD22-A114 – Microphone Input	±300		V

### Note:

1. This device is fabricated using CMOS technology and is therefore susceptible to damage from electrostatic discharges. Appropriate precautions must be taken during handling and storage of this device to prevent exposure to ESD.

## Reliability Information

Symbol	Parameter	Min.	Typ.	Max.	Unit
T <sub>J</sub>	Junction Temperature			+150	°C
T <sub>STG</sub>	Storage Temperature Range	-65		+125	°C
T <sub>RFLW</sub>	Peak Reflow Temperature			+260	°C
θ <sub>JA</sub>	Thermal Resistance, JEDEC Standard, Multilayer Test Boards, Still Air		90		°C/W

## Recommended Operating Conditions

The Recommended Operating Conditions table defines the conditions for actual device operation. Recommended operating conditions are specified to ensure optimal performance to the datasheet specifications. Fairchild does not recommend exceeding them or designing to Absolute Maximum Ratings.

Symbol	Parameter	Min.	Typ.	Max.	Unit
T <sub>A</sub>	Operating Temperature Range	-30		+85	°C
V <sub>DD</sub>	Supply Voltage Range	1.64	1.80	3.63	V
t <sub>RF-CLK</sub>	Clock Rise and Fall Time			10	ns

## Device Specific Electrical Characteristics

Unless otherwise specified, all limits are guaranteed for  $T_A=25^\circ\text{C}$ ,  $V_{DD}=1.8\text{ V}$ ,  $V_{IN}=94\text{ dB (SPL)}$ , and  $f_{CLK}=2.4\text{ MHz}$ . Duty Cycle=50% and  $C_{MIC}=15\text{ pF}$ .

Symbol	Parameter	FAN3850AUC16X			Unit
		Min.	Typ.	Max.	
SNR	Signal-to-Noise Ratio $f_{IN}=1\text{ kHz (1Pa)}$ , A-Weighted		62		dB(A)
$e_N$	Total Input RMS Noise <sup>(3)</sup> 20Hz to 20kHz, A-Weighted		5.74	6.80	$\mu\text{V}_{RMS}$
$V_{IN}$	Maximum Input Signal $f_{IN}=1\text{ kHz}$ , THD+N < 10%, Level=0V			448	mV <sub>PP</sub>

## Electrical Characteristics

Unless otherwise specified, all limits are guaranteed for  $T_A=25^\circ\text{C}$ ,  $V_{DD}=1.8\text{ V}$ ,  $V_{IN}=94\text{ dB (SPL)}$ , and  $f_{CLK}=2.4\text{ MHz}$ . Duty Cycle=50% and  $C_{MIC}=15\text{ pF}$ .

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
$V_{DD}$	Supply Voltage Range		1.64	1.80	3.63	V
$I_{DD}$	Supply Current	INPUT=AC Coupled to GND, CLOCK=On, No Load		470		$\mu\text{A}$
$I_{SLEEP}$	Sleep Mode Current	$f_{CLK}=\text{GND}$		1.5	8.0	$\mu\text{A}$
PSR	Power Supply Rejection <sup>(3)</sup>	INPUT=AC Coupled to GND, Test Signal on $V_{DD}=217\text{ Hz}$ Square Wave and Broadband Noise <sup>(2)</sup> , Both 100mV <sub>P-P</sub>		-74		dBFS
$I_{NOM}$	Nominal Sensitivity <sup>(4)</sup>	INPUT=94 dB SPL (1Pa)		-26		dBFS
THD	Total Harmonic Distortion <sup>(6)</sup>	$f_{IN}=1\text{ kHz}$ , INPUT=-26 dBFS		0.02	0.20	%
THD+N	THD and Noise <sup>(3)</sup>	$50\text{ Hz} \leq f_{IN} \leq 1\text{ kHz}$ , INPUT=-20 dBFS		0.2	1.0	%
		$f_{IN}=1\text{ kHz}$ , INPUT=-5 dBFS		1.0	5.0	
		$f_{IN}=1\text{ kHz}$ , INPUT=0 dBFS		5.0	10.0	
$C_{IN}$	Input Capacitance <sup>(7)</sup>	INPUT		0.2		pF
$R_{IN}$	Input Resistance <sup>(7)</sup>	INPUT	>100			G $\Omega$
$V_{IL}$	CLOCK & SELECT Input Logic LOW Level				0.3	V
$V_{IH}$	CLOCK & SELECT Input Logic HIGH Level		1.5		$V_{DD}+0.3$	V
$V_{OL}$	Data Output Logic LOW Level				$0.35 \cdot V_{DD}$	V
$V_{OH}$	Data Output Logic HIGH Level		$0.65 \cdot V_{DD}$			V
$V_{OUT}$	Acoustic Overload Point <sup>(7)</sup>	THD < 10%	120			dB SPL

Continued on the following page...

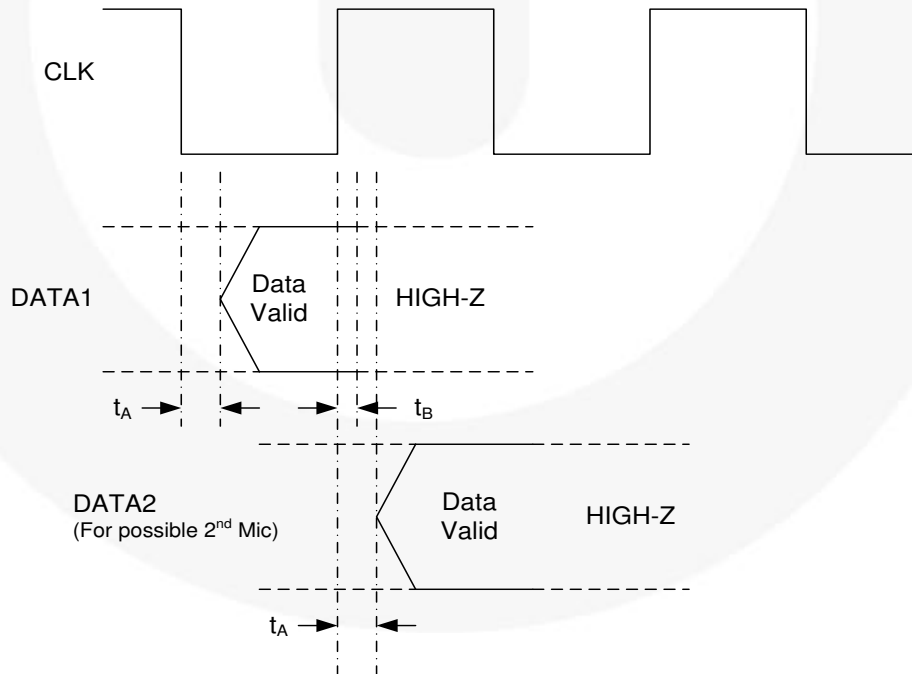
### Electrical Characteristics (Continued)

Unless otherwise specified, all limits are guaranteed for  $T_A=25^\circ\text{C}$ ,  $V_{DD}=1.8\text{ V}$ ,  $V_{IN}=94\text{ dB(SPL)}$ , and  $f_{CLK}=2.4\text{ MHz}$ .  
Duty Cycle=50% and  $C_{MIC}=15\text{ pF}$ .

Symbol	Parameter	Condition	Min.	Typ.	Max.	Unit
$t_A$	Time from CLOCK Transition to Data becoming Valid	On Falling Edge of CLOCK, SELECT=GND, $C_{LOAD}=15\text{ pF}$	18	43		ns
$t_B$	Time from CLOCK Transition to Data becoming HIGH-Z	On Rising Edge of CLOCK, SELECT=GND, $C_{LOAD}=15\text{ pF}$	0	5	16	ns
$t_A$	Time from CLOCK Transition to Data becoming Valid	On Rising Edge of CLOCK, SELECT= $V_{DD}$ , $C_{LOAD}=15\text{ pF}$	18	56		ns
$t_B$	Time from CLOCK Transition to Data becoming HIGH-Z	On Falling Edge of CLOCK, SELECT= $V_{DD}$ , $C_{LOAD}=15\text{ pF}$	0	5	16	ns
$f_{CLK}$	Input CLOCK Frequency <sup>(8)</sup>	Active Mode	1.0	2.4	4.0	MHz
$CLK_{dc}$	CLOCK Duty Cycle <sup>(3)</sup>		40	50	60	%
$t_{WAKEUP}$	Wake-Up Time <sup>(9)</sup>	$f_{CLK}=2.4\text{ MHz}$		0.35	2.00	ms
$t_{FALLASLEEP}$	Fall-Asleep Time <sup>(10)</sup>	$f_{CLK}=2.4\text{ MHz}$	0	0.01	1.00	ms
$C_{LOAD}$	Load Capacitance on Data				100	pF

**Notes:**

2. Pseudo-random noise with triangular probability density function. Bandwidth up to 10 MHz.
3. Guaranteed by characterization.
4. Assuming that 120 dB(SPL) is mapped to 0 dBFS.
5. Assuming an input of -45 dBV.
6. Guaranteed by design.
7. All parameters are tested at 2.4 MHz. Frequency range guaranteed by characterization.
8. Device wakes up when  $f_{CLK} \geq 300\text{ kHz}$ .
9. Device falls asleep when  $f_{CLK} \leq 70\text{ kHz}$ .

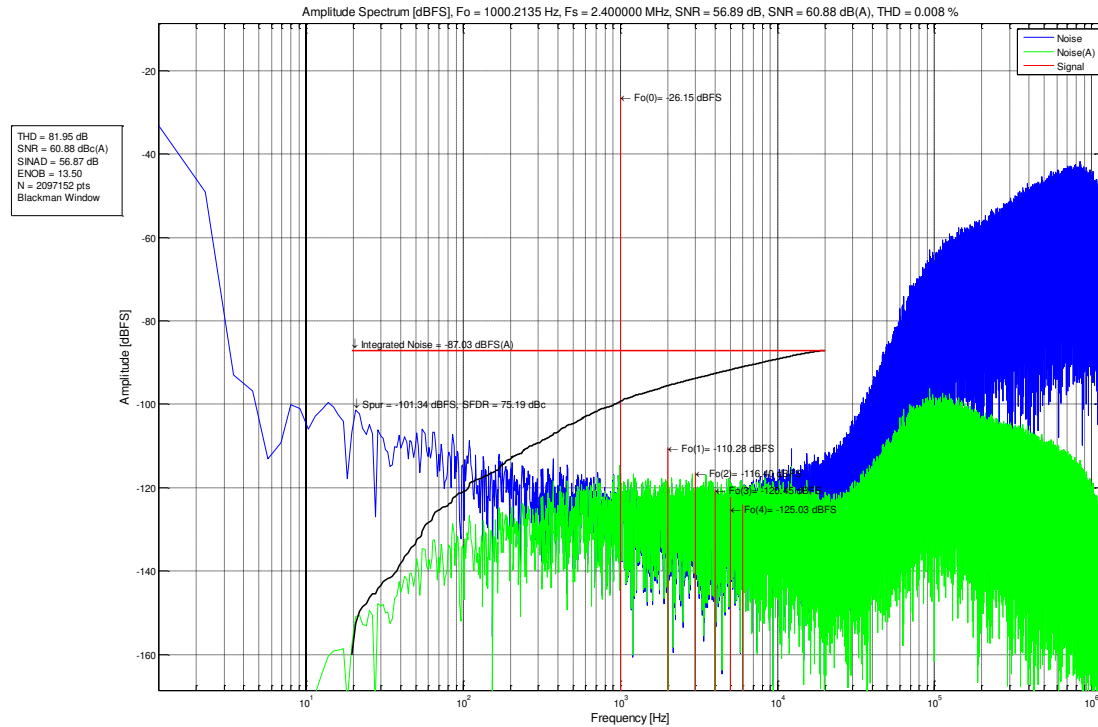


$t_A$  – Microphone delay from clock edge to data assertion.  
 $t_B$  – Microphone delay from clock edge to high-impedance state.  
 $t_A > t_B$  to have interim HIGH-Z state in both signals.

**Figure 3. Interface Timing**

### Typical Performance Characteristics

Unless otherwise specified, all limits are guaranteed for  $T_A=25^\circ\text{C}$ ,  $V_{DD}=1.8\text{ V}$ ,  $V_{IN}=94\text{ dB(SPL)}$ ,  $f_{CLK}=2.4\text{ MHz}$ , and duty cycle=50%.



Filename: fan3850a-1-BD9\_M-20110125T122914.dat

Figure 4. Noise vs. Frequency

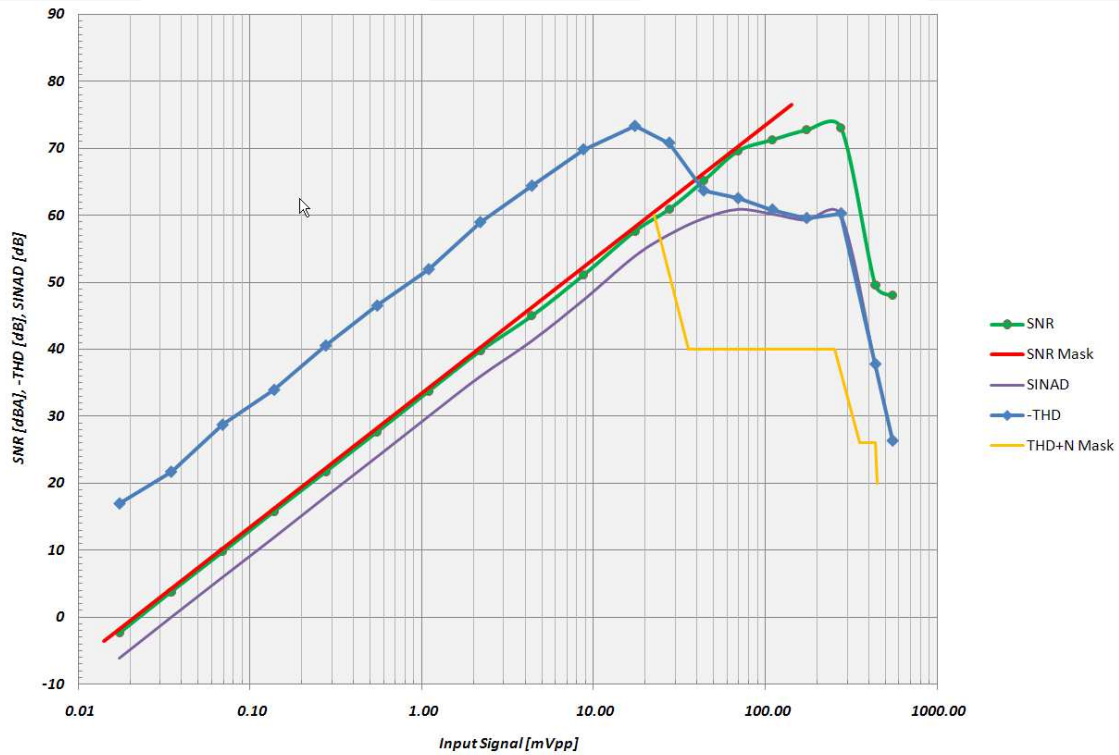


Figure 5. THD, SINAD, and SNR vs. Input Amplitude



Typical Performance Characteristics (Continued)

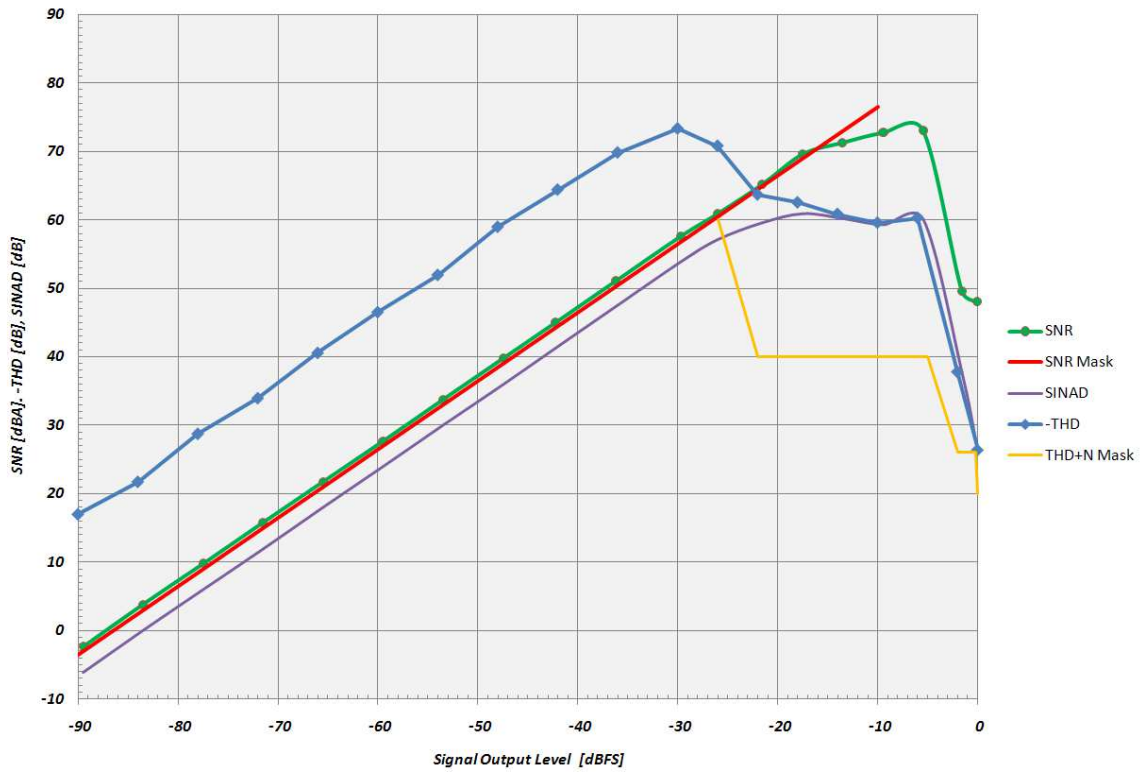


Figure 6. THD, SINAD, and SNR vs. Output Level

Temp (°C)	Delta(dB)
-40	0.1971
-30	0.1644
-20	0.1260
-10	0.0954
0	0.0657
10	0.0359
20	0.0139
25	0.0000
30	-0.0097
40	-0.0344
50	-0.0514
60	-0.0739
70	-0.0998
80	-0.1183
85	-0.1271

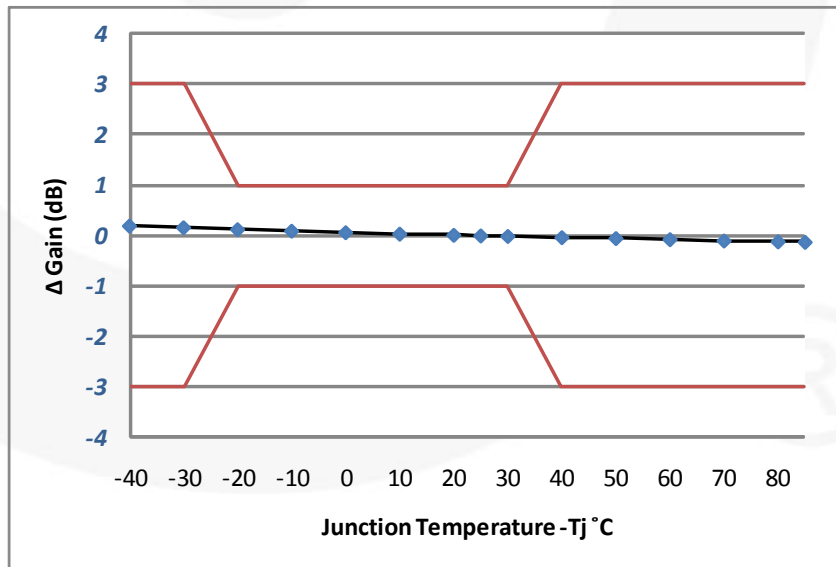


Figure 7. Δ Gain vs. Temperature (Nominal Temperature= 25°C)

Applications Information

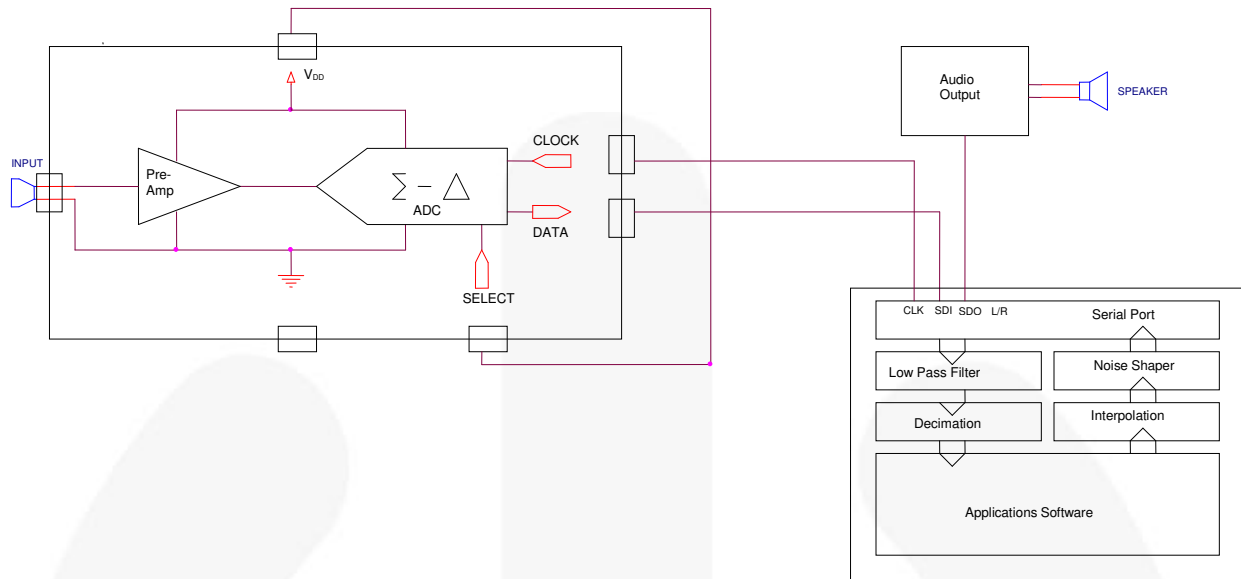


Figure 8. Mono Microphone Application Circuit

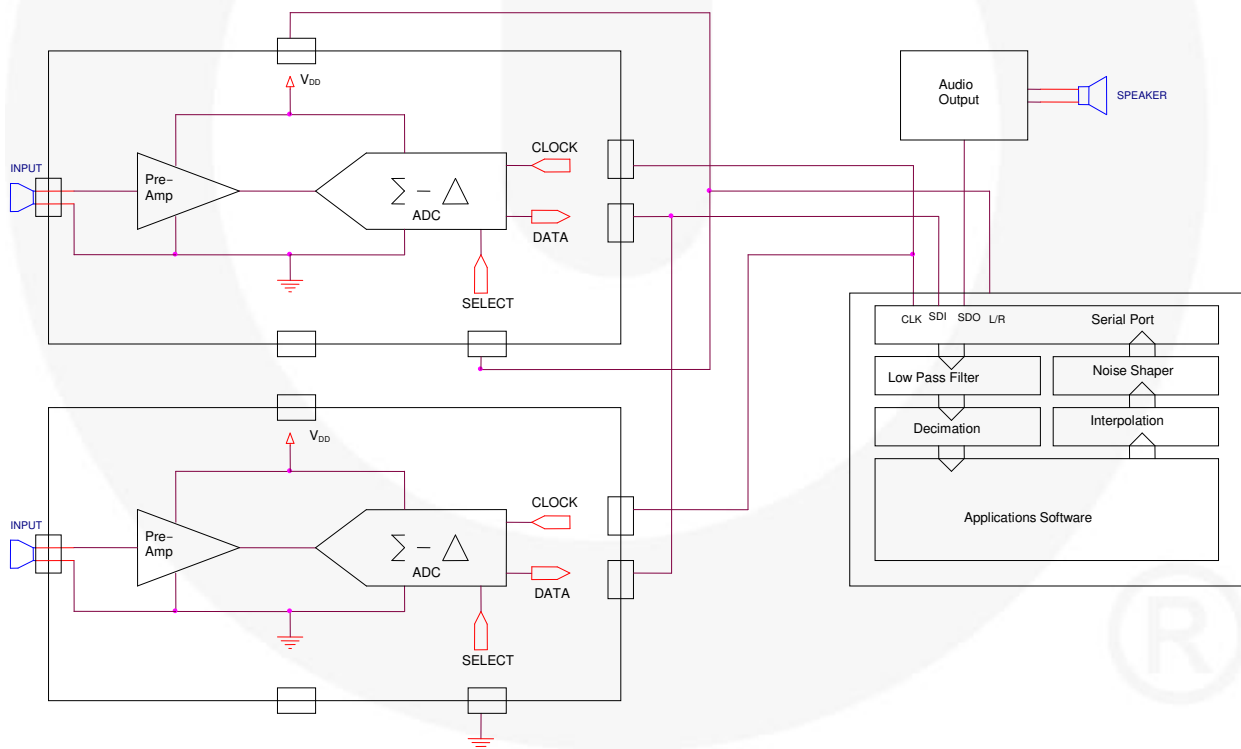
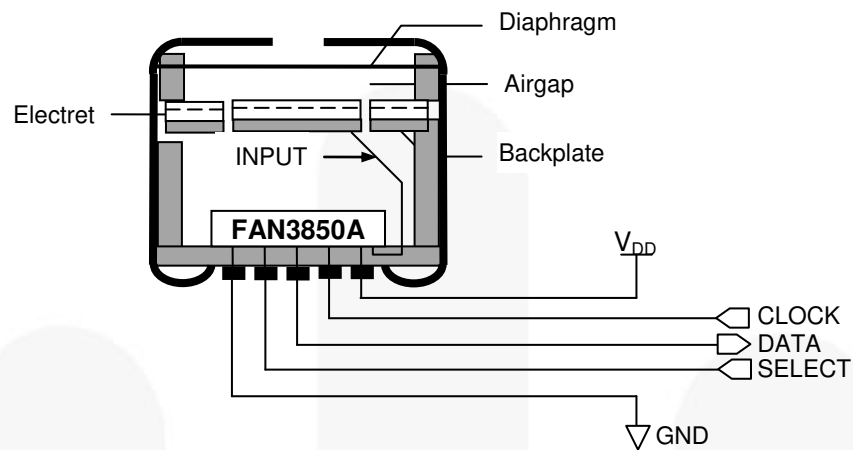


Figure 9. Stereo Microphone Application Circuit

**Applications Information** (Continued)



**Figure 10. MIC Element Drawing**

A 0.1  $\mu\text{F}$  decoupling capacitor is required for  $V_{\text{DD}}$ . It can be located inside the microphone or on the PCB very close to the  $V_{\text{DD}}$  pin.

Due to high input impedance, care should be taken to remove all flux used during the reflow soldering process.

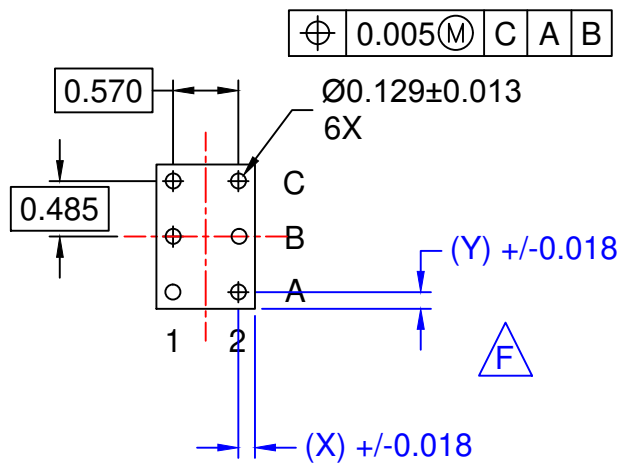
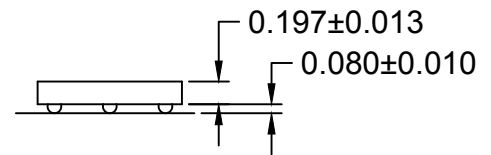
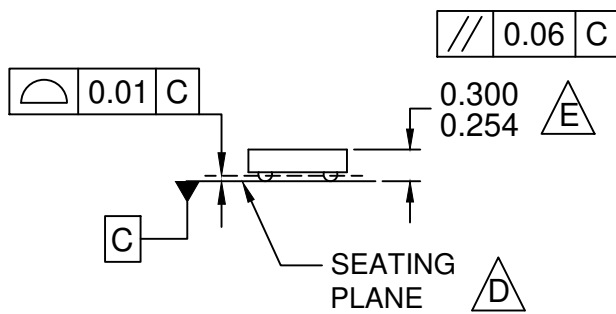
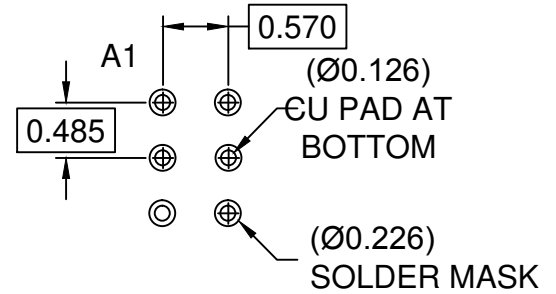
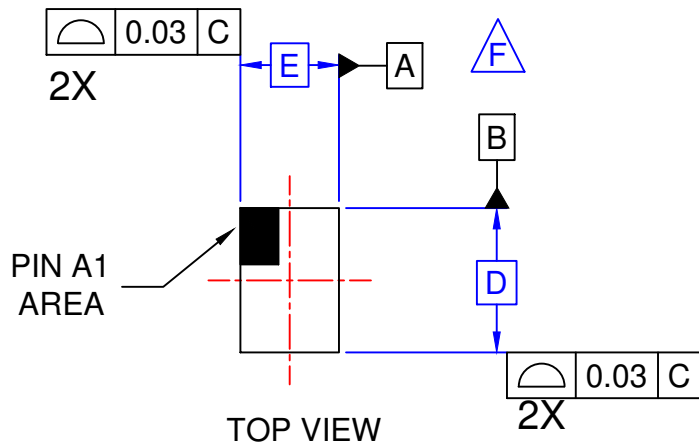
A 100  $\Omega$  resistance is recommended on the clock output of the device driving the FAN3850A to minimize ringing and improve signal integrity.

For optimal PSR, route a trace to the  $V_{\text{DD}}$  pin. Do not place a  $V_{\text{DD}}$  plane under the device.

The table below pertains to the Marketing Outline drawing on the following page.

**FAN3850A External Product Dimensions**

Product ID	D	E	X	Y
All options	1.260mm	0.860mm	0.145mm	0.145mm



NOTES:

- A. NO JEDEC REGISTRATION APPLIES.
- B. DIMENSIONS ARE IN MILLIMETERS.
- C. DIMENSIONS AND TOLERANCES PER ASME Y14.5M, 2009.
- D. DATUM C, THE SEATING PLANE IS DEFINED BY THE SPHERICAL CROWNS OF THE BALLS.
- E. PACKAGE TYPICAL HEIGHT IS 273 MICRONS ±23 MICRONS (254-300 MICRONS).
- F. FOR DIMENSIONS D, E, X, AND Y SEE PRODUCT DATASHEET.
- G. DRAWING FILENAME: UC006AHrev4.



ON Semiconductor and  are trademarks of Semiconductor Components Industries, LLC dba ON Semiconductor or its subsidiaries in the United States and/or other countries. ON Semiconductor owns the rights to a number of patents, trademarks, copyrights, trade secrets, and other intellectual property. A listing of ON Semiconductor's product/patent coverage may be accessed at [www.onsemi.com/site/pdf/Patent-Marking.pdf](http://www.onsemi.com/site/pdf/Patent-Marking.pdf). ON Semiconductor reserves the right to make changes without further notice to any products herein. ON Semiconductor makes no warranty, representation or guarantee regarding the suitability of its products for any particular purpose, nor does ON Semiconductor assume any liability arising out of the application or use of any product or circuit, and specifically disclaims any and all liability, including without limitation special, consequential or incidental damages. Buyer is responsible for its products and applications using ON Semiconductor products, including compliance with all laws, regulations and safety requirements or standards, regardless of any support or applications information provided by ON Semiconductor. "Typical" parameters which may be provided in ON Semiconductor data sheets and/or specifications can and do vary in different applications and actual performance may vary over time. All operating parameters, including "Typicals" must be validated for each customer application by customer's technical experts. ON Semiconductor does not convey any license under its patent rights nor the rights of others. ON Semiconductor products are not designed, intended, or authorized for use as a critical component in life support systems or any FDA Class 3 medical devices or medical devices with a same or similar classification in a foreign jurisdiction or any devices intended for implantation in the human body. Should Buyer purchase or use ON Semiconductor products for any such unintended or unauthorized application, Buyer shall indemnify and hold ON Semiconductor and its officers, employees, subsidiaries, affiliates, and distributors harmless against all claims, costs, damages, and expenses, and reasonable attorney fees arising out of, directly or indirectly, any claim of personal injury or death associated with such unintended or unauthorized use, even if such claim alleges that ON Semiconductor was negligent regarding the design or manufacture of the part. ON Semiconductor is an Equal Opportunity/Affirmative Action Employer. This literature is subject to all applicable copyright laws and is not for resale in any manner.

## PUBLICATION ORDERING INFORMATION

### LITERATURE FULFILLMENT:

Literature Distribution Center for ON Semiconductor  
19521 E. 32nd Pkwy, Aurora, Colorado 80011 USA  
**Phone:** 303-675-2175 or 800-344-3860 Toll Free USA/Canada  
**Fax:** 303-675-2176 or 800-344-3867 Toll Free USA/Canada  
**Email:** [orderlit@onsemi.com](mailto:orderlit@onsemi.com)

**N. American Technical Support:** 800-282-9855 Toll Free  
USA/Canada  
**Europe, Middle East and Africa Technical Support:**  
Phone: 421 33 790 2910  
**Japan Customer Focus Center**  
Phone: 81-3-5817-1050

**ON Semiconductor Website:** [www.onsemi.com](http://www.onsemi.com)  
**Order Literature:** <http://www.onsemi.com/orderlit>  
For additional information, please contact your local  
Sales Representative